

Transfer Molding System

Model YPM1120



**Transfer molding system
for automotive and power packages**

Transfer molding system for automotive and power packages

- Supports a wide range of automotive products (e.g. power modules, ECUs and sensors).
- Independent upper and lower pin mechanism enables high-precision molding customized for the product.
- Separated upper/lower drive sources enables higher AC servo precision control.
- Modular concept to adapt to different production quantities.



English



SPECIFICATION

Items			Unit	Description											
Model			—	YPM1120											
Machine type			—	Upper moving pin specification				Lower moving pin specification				Vertial moving pin specification			
Workpiece type			—	Substrate・Lead frame											
Workpiece size	Length		mm	150—290											
	Width		mm	35—100											
Molding compound	Diameter		mm	φ 13, 14, 16, 18, 20											
	Length		mm	14.3—35.0											
Machine time			sec	Approximately 40				Approximately 40 (45*)							
External dimensions	Number of press moules		module	1	2	3	4	1	2	3	4	1	2	3	4
	Stack magazine type	Width	mm	2,540	3,220	3,900	4,580	2,540	3,220	3,900	4,580	2,540	3,220	3,900	4,580
		Depth	mm	1,665				1,765				1,765			
		Height	mm	1,980 (Press 2,245)				2,185 (Press 2,185)				2,185 (Press 2,450)			
	Slit magazine type	Width	mm	2,540	3,220	3,900	4,580	2,540	3,220	3,900	4,580	2,540	3,220	3,900	4,580
		Depth	mm	2,000				2,000				2,000			
		Height	mm	1,980 (Press 2,245)				2,185 (Press 2,185)				2,185 (Press 2,450)			
	Weight	Stack magazine type		ton	6.0	9.4	12.8	16.2	6.6 (6.7*)	10.2 (10.4*)	13.8 (14.1*)	17.4 (17.8*)	6.8 (6.9*)	10.6 (10.8*)	14.4 (14.7*)
Slit magazine type		ton	6.3	9.7	13.1	16.5	7.0 (7.1*)	10.6 (10.8*)	14.2 (14.5*)	17.8 (18.2*)	7.2 (7.3*)	11.0 (11.2*)	14.8 (15.1*)	18.6 (19.0*)	
Numberof workpieces per cycle			workpiece	2	4	6	8	2	4	6	8	2	4	6	8
Input magazine setting space			mm	440											
Output magazine capacity (Stack magazine type)			pcs	2											
Output magazine space (Slit magazine type)			mm	440											
Clamp capacity			kN／(tf)	196.0—1,177.0／20.0—120.0											
Transfer capacity			kN／(tf)	3.92—49.0／0.4—5.0 (2 step pressure setting)											
Conversion method to different product type			—	“Conversion kit” method											
Mountable mold			—	XXL											
Upper release film width			mm	—				100—300* (Please consult us for the vertial moving pin specification.)							

- The figures shown above are based on standard machine specifications.
- The above specification are subject to change without prior notice.
- For special requirements, please consult your local TOWA representative.
- * means specification in case of release film type.



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